

# **Specification for TFT**

## AFY1280800A0-10.1INTH-R



**Revision B** 

А	Orient Display
FY	ТFТ Туре
1280800	Resolution 1280 x 800
A0	Serial A0
10.1	10.1", Module Dimension 228.85 x 152.74 x 6.70 mm
1	IPS Display
Ν	Top: -20~+70°C; Tstr: -30~+80°C
Т	Transmissive
Н	High Brightness, 800 cd/m2
R	Resistive Touch Panel
/	Controller <u>HX8695-A</u> + <u>HX8288-A</u> Or Compatible
1	LVDS Interface













### **REVISION RECORD**

Rev No.	Rev date	Contents	Remarks
0	2019.12.03	First release	Preliminary
А	2019.12.25	Update EXTERNAL DIMENSIONS	Page 5
В	2020.4.14	Change backlight detail as in page 4 <sup>th</sup>	Page 4
L	l		

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CONTENTS
1. GENERAL INFORMATION 4
2. ABSOLUTE MAXIMUM RATINGS 4
3. ELECTRICAL CHARACTERISTICS 4
4. BACKLIGHT CHARACTERISTICS 4
5. EXTERNAL DIMENSIONS
6. ELECTRO-OPTICAL CHARACTERISTICS
7. INTERFACE DESCRIPTION
8.OPERATION SPECIFICATIONS10
9. POWER SEQUENCE
10. RELIABILITY TEST CONDITIONS
11. INSPECTION CRITERION
12. HANDLING PRECAUTIONS
13. PRECAUTION FOR USE
14. PACKING SPECIFICATION

### **1. GENERAL INFORMATION**

No.	Item	Contents	Unit
1	LCD size	10.1 inch (Diagonal)	/
2	LCD type	IPS/Normally black/Transmissive	/
3	Viewing direction(eye)	Free	/
4	Gray scale inversion direction	-	/
5	Resolution(H*V)	1280*800 Pixels	/
6	Module size (L*W*H)	228.85*152.74*6.70	mm
7	Active area (L*W)	216.96*135.60	mm
8	Pixel pitch (L*W)	0.1695* 0.1695	mm
9	Interface type	LVDS interface	/
10	Color Depth	16.7M	/
11	Module power consumption	TBD	W
12	Back light type	LED	/
13	Weight	TBD	g

### 2. ABSOLUTE MAXIMUM RATINGS

ltem	Symbol	Min.	Max.	Unit	Note
Power supply input voltage for TFT	VDD	-0.3	+3.9	V	
Backlight current (normal temp.)	ILED	-	225	mA	
Operation temperature	Тор	-20	+70	°C	Note1
Storage temperature	Tst	-30	+80	°C	Note1
Humidity	RH	20%	90%	/	Note1

### 3. ELECTRICAL CHARACTERISTICS

### DC CHARACTERISTICS(at Ta=25°C)

Item	Symbol	Min.	Тур.	Max.	Unit	Note
Power supply input voltage(TFT Module)	VDD	2.3	2.5	2.7	V	
Power supply current	IVDD	-	277	-	mA	
LVDS Differential input high Threshold voltage	R <sub>XVTH</sub>	-	-	+100	mV	R <sub>XVCM</sub>
LVDS Differential input low Threshold voltage	R <sub>XVTL</sub>	-100	-	-	mV	=1.2V
LVDS Differential input common mode voltage	R <sub>XVCM</sub>	0.7	-	1.6	V	
LVDS Differential voltage	VID	200	-	600	mV	

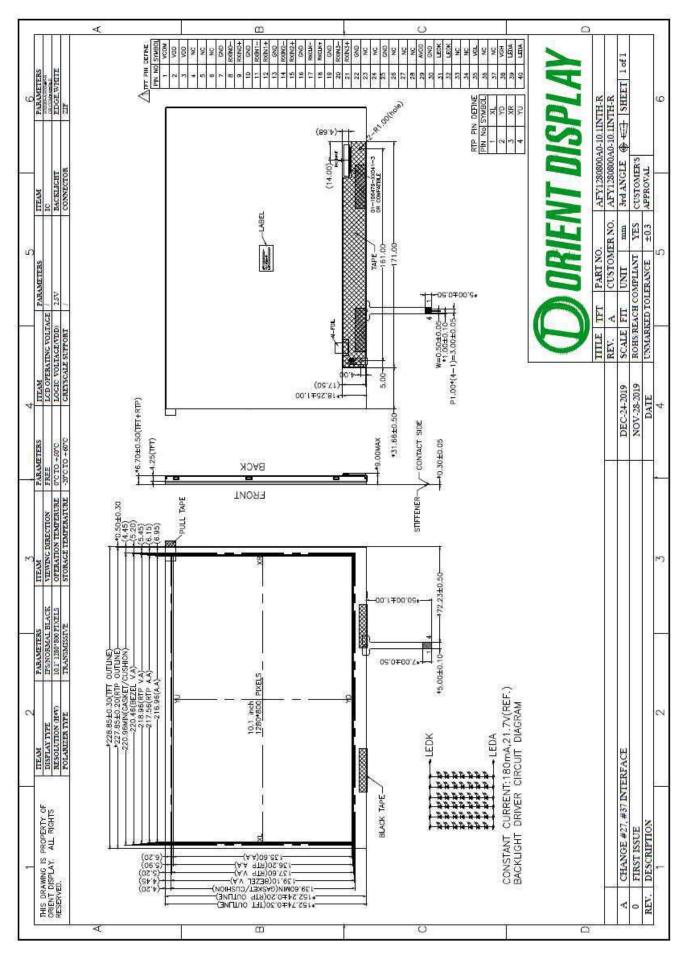
## 4. BACKLIGHT CHARACTERISTICS

Symbol	Min.	Тур.	Max.	Unit	Note
VF	20.3	21.7	23.1	V	
IF	-	180	-	mA	
PLED	-	3.906	-	W	Note1
-		42		PCS	
-	7 in ser	ies 6 in para	allel	/	
-	20000	-	-	Hrs	Note2
	VF IF PLED	VF         20.3           IF         -           PLED         -           -         -           -         7 in ser           -         20000	VF         20.3         21.7           IF         -         180           PLED         -         3.906           -         42           -         7 in series         6 in para           -         20000         -	VF         20.3         21.7         23.1           IF         -         180         -           PLED         -         3.906         -           -         42         -         -           -         7 in series         6 in parallel         -           -         20000         -         -         -	VF         20.3         21.7         23.1         V           IF         -         180         -         mA           PLED         -         3.906         -         W           -         42         PCS           -         7 in series         6 in parallel         /           -         20000         -         -         Hrs

Note1 : Calculator value for reference : IF\*VF = PLED

Note2 : The LED life-time define as the estimated time to 50% degradation of initial brightness at Ta= $25^{\circ}$ C and IF =180mA. The LED lifetime could be decreased if operating IF is larger than 260mA.

### 5. EXTERNAL DIMENSIONS



### 6. ELECTRO-OPTICAL CHARACTERISTICS

Item	Symbol	Condition	Min.	Тур.	Max.	Unit	Remark	Note
Response time	Tr+ Tf		-	25	50	ms	FIG.1	Note 4
Contrast ratio	Cr	-	600	800	-	-	FIG.2	Note 1
Surface Iuminance	Lv	θ=0°	600	800	-	cd/m <sup>2</sup>	FIG.2	Note 2
Luminance uniformity	Yu	θ=0°	75	80	-	%	FIG.2	Note 3
NTSC	-	θ=0°	-	50	-	%	FIG.2	Note 5
		Ø <b>=</b> 90°	75	85	-	deg	FIG.3	Noto 6
	θ	Ø <b>=</b> 270°	75	85	-	deg	FIG.3	
Viewing angle		Ø <b>=0°</b>	75	85	-	deg	FIG.3	Note 6
		Ø=180°	75	85	-	deg	FIG.3	
	Red x			TBD		-		
	Red y			TBD		-		
	Green x	0.00		TBD		-		
CIE (x,y)	Green y	θ=0°	Тур	TBD	Тур	-	FIG.2	Noto F
chromaticity	Blue x	Ø=0° Ta=25°C	-0.04	TBD	+0.04	-	CIE1931	Note 5
	Blue y	10-20 0		TBD		-	]	
	White x			TBD		-		
	White y			TBD		-	1	

#### Note1.Definition of contrast ratio

Contrast ratio(Cr) is defined mathematically by the following formula.

For more information see FIG.2.

Contrast ratio= Luminance measured when LCD on the "White" state Luminance measured when LCD on the "Black" state

Measured at the center area of the LCD

#### Note2.Definition of surface luminance

Surface luminance is the luminance with all pixels displaying white.

For more information see FIG.2.

Lv = Average Surface Luminance with all white pixels(P1,P2,P3, .....,Pn)

#### Note3.Definition of luminance uniformity

The luminance uniformity in surface luminance is determined by measuring luminance at each test position 1 through n, and then dividing the maximum luminance of n points luminance by minimum luminance of n points luminance.For more information see FIG.2.

Minimum surface luminance with all white pixels (P1,P2,P3,.....,Pn) Yu =

Maximum surface luminance with all white pixels (P1,P2,P3,.....,Pn)

#### Note4. Definition of response time

The response time is defined as the LCD optical switching time interval between "White" state and "Black" state. Rise time  $(T_{ON})$  is the time between photo detector output intensity changed from 90% to 10%. And fall time (T<sub>OFF</sub>) is the time between photo detector output intensity changed from 10% to 90%. For additional information see FIG1.

#### Note5. Definition of color chromaticity (CIE1931)

CIE (x,y) chromaticity, The x,y value is determined by screen active area center position P5. For more information see FIG.2.

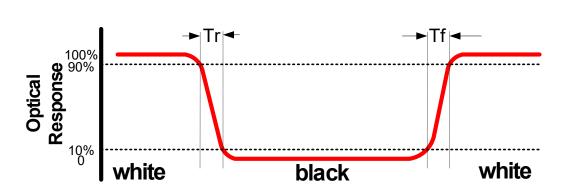
#### Note6. Definition of viewing angle

Viewing angle is the angle at which the contrast ratio is greater than 10. angles are determined for the horizontal or x axis and the vertical or y axis with respect to the z axis which is normal to the LCD surface. For more information see FIG.3.

For viewing angle and response time testing, the testing data is base on Autronic-Melchers's ConoScope or DMS series Instruments or compatible. For contrast ratio, Surface Luminance, Luminance uniformity and CIE, the testing data is base on TOPCON's BM-5or BM-7 photo detector or compatible.

**Note:** For TFT module, Gray scale reverse occurs in the direction of panel viewing angle.

#### FIG.1. The definition of response Time



## FIG.2. Measuring method for contrast ratio, surface luminance, luminance uniformity, CIE (x,y) chromaticity

Size :  $S \le 5$ "(see Figure a) A : 5 mm B : 5 mm H,V : Active area Light spot size  $\emptyset = 5$ mm(BM-5) or  $\emptyset = 7.7$ mm (BM-7)50cm distance or compatible distance from the LCD surface to detector lens. test spot position : see Figure a. measurement instrument : TOPCON's luminance meter BM-5 or BM-7 or compatible (see Figure c).

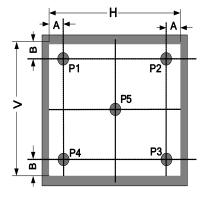
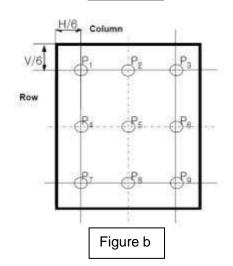


Figure a

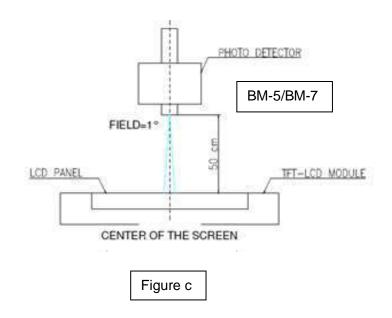


Size : 5"  $\leq$  S  $\leq$  12.3"(see Figure b)

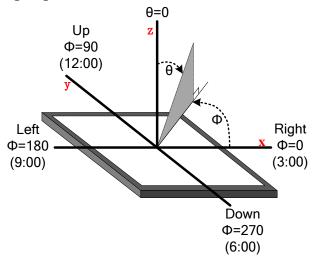
H,V : Active area

Light spot size  $\emptyset$ =5mm(BM-5) or  $\emptyset$ =7.7mm (BM-7)50cm distance or compatible distance from the LCD surface to detector lens. test spot position : see Figure b.

measurement instrument : TOPCON's luminance meter BM-5 or BM-7 or compatible (see Figure c).



### FIG.3. The definition of viewing angle



### 7. INTERFACE DESCRIPTION

TFT Module Interface description

Interface NO.	NAME	I/O or connect to	DESCRIPTION
1	VCOM	Р	Power Ground
2~3	VDD	Р	LCD power supply(Typ.3.3V)
4	NC	/	No connection
5	NC	/	No connection
6	NC	/	No connection
7	GND	I	Power Ground
8	RXin0-	I	LVDS CH0 data signal(-)
9	RXin0+	I	LVDS CH0 data signal(+)
10	GND	Р	Power Ground
11	RXin1-	I	LVDS CH1 data signal(-)
12	RXin1+	I	LVDS CH1 data signal(+)
13	GND	Р	Power Ground
14	RXin2-	I	LVDS CH2 data signal(-)
15	RXin2+	I	LVDS CH2 data signal(+)
16	GND	Р	Power Ground
17	CLKIN-	I	LVDS CLK data signal(-)
18	CLKIN+	I	LVDS CLK data signal(+)
19	GND	Р	Power Ground

AFY1280800A0-10.1INTH-R

20	RXin3-	I	LVDS CH3 data signal(-)
21	RXin3+	I	LVDS CH3 data signal(+)
22	GND	Р	Power Ground
23-24	NC	/	No connection
25	GND	Р	Power Ground
26	NC	/	No connection
27	NC	/	No connection
28	NC	/	No connection
29	AVDD	Р	Power for Analog circuit
30	GND	Р	Power Ground
31	LEDK	Р	
32	LEDK	Р	<ul> <li>Backlight Cathode</li> </ul>
33	NC	/	No connection
34	NC	/	No connection
35	VGL	Р	Gate off voltage
36	NC	/	No connection
37	NC	/	No connection
38	VGH	Р	Gate on voltage
39	LEDA	Р	Deeldight Anada
40	LEDA	Р	Backlight Anode

### **RTP Interface description**

Interface NO.	NAME	I/O or connect to	DESCRIPTION
1	XL	I	X-Left
2	YD	I	Y-Down
3	XR	I	X-Right
4	YU	I	Y-Up

### 8. OPERATION SPECIFICATIONS

### 8.1 absolute maximum ratings

lite an	Cumhal	(Note 1) Val	ues	Unit	Domonik
ltem	Symbol	Min.	Max.	Unit	Remark
	VDD	-0.3	3.9	V	
	AVDD	-0.3	14	V	
Power voltage	$V_{GH}$	-0.3	42.0	V	
	V <sub>GL</sub>	-19	0.3	V	
	V <sub>GH</sub> -V <sub>GL</sub>	12	40.0	V	
Operation Temperature	T <sub>OP</sub>	-20	70	°C	
Storage Temperature	T <sub>ST</sub>	-30	80	°C	

Note 1: The absolute maximum rating values of this product are not allowed to be exceeded at any times. Should a module be used with any of the absolute maximum ratings exceeded, the characteristics of the module may not be recovered, or in an extreme case, the module may be permanently destroyed.

### 8.2 Typical Operation Conditions

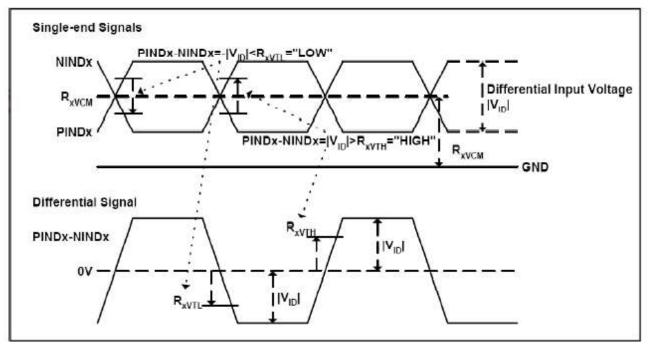
		Values		unit	remark	
	Min.	Тру.	Max.			
VDD	2.3	2.5	2.7	V	Note1	
AVDD	8.0	8.2	8.4	V		
Vgh	21.7	22.0	22.3	V		
Vgl	-7.3	-7.0	-6.7	V		
VCOM	2.7	3	3.3	V	Note2	
Vih	0.8VDD	-	3.6	V	Note2	
Vil	0	-	0.2DVdd	V	Note3	

Note 1: Be sure to apply VDD and  $V_{GL}$  to the LCD first, and then apply  $V_{GH}$ .

Note 2: VDD setting should match the signals output voltage (refer to Note 3) of customer's system board.

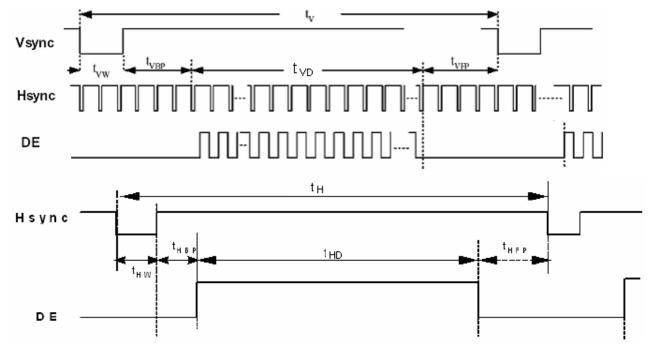
Note 4: Typical VCOM is only a reference value, it must be optimized according to each LCM. Be sure to use VR.

### 8.3 AC CHARACTERISTICS 8.3.1 ac electrical characteristics

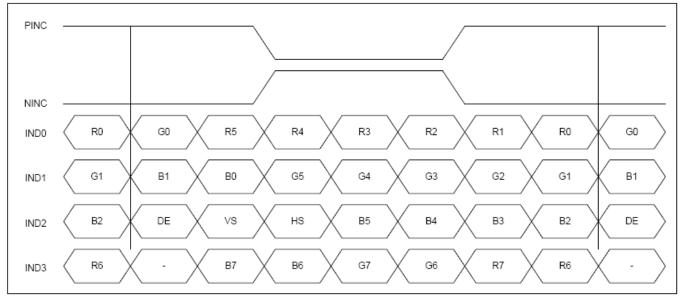


### 8.3.2Timing table

ltem	Symbol		Values	Unit	Remark	
item	Symbol	Min.	Тур.	Тур. Мах.		Remark
Clock Frequency	1/Tc	68.9	71.1	73.4	MHz	Frame rate =60Hz
Horizontal display area	thd		1280			
HS period time	tн	1410	1440	1470	Тс	
HS Width +Back Porch +Front Porch	tнw+ tнвр +tнгр	60	160	190	Тс	
Vertical display area	t∨D		800			
∨S period time	tv	815	823	833	tн	
VS Width +Back Porch +Front Porch	tvw+ tvBP +tvFP	15	23	33	tн	

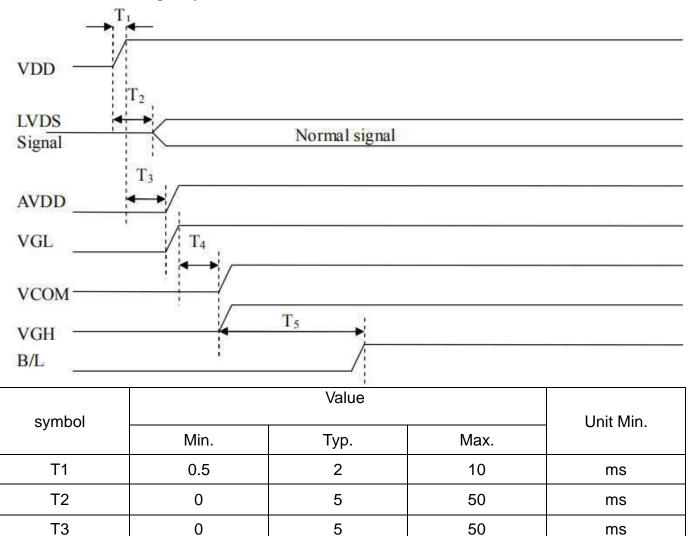






### 9. POWER SEQUENCE

9.1 Power on timing sequence



6

130

100

200

Τ4

T5

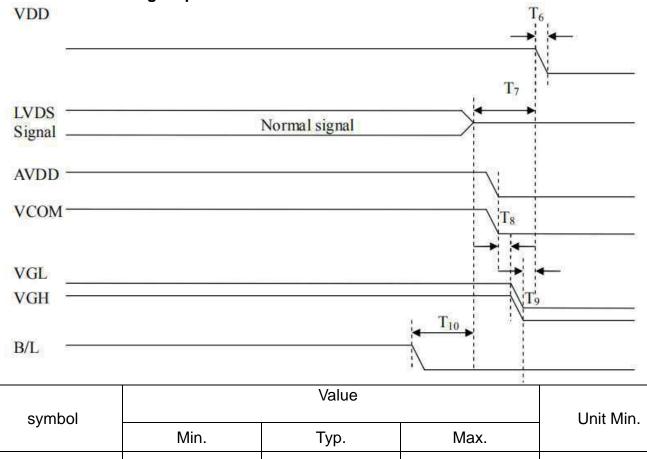
0

120

ms

ms

### 9.2 Power off timing sequence



2

7

5

1

2

10

50

10

10

100

ms

ms

ms

ms

ms

Τ6

Τ7

Τ8

Т9

T10

0.5

0

0

0

0

### **10. RELIABILITY TEST CONDITIONS**

No.	Test item	Test con	dition	Inspection after test	
10.1	High temperature storage test	+60C/240 hours			
10.2	Low temperature storage test	-20°C/240 hours			
10.3	High temperature operating test	+50°C/120 hours	+50°C/120 hours		
10.4	Low temperature operating test	0°C/120 hours		Inspection after	
10.5	Temperature cycle storage test	0°C ~ 25°C ~ +50°C/10cycles (30min ) (10min ) (30min )		2~4hours storage at room temperature, the	
10.6	High temperature high humidity test	+40°C*90% RH/120 hours		sample shall be free from defects : 1.Current changing	
10.7	Vibration test	Frequency : 250 r/min Amplitude : 1 inch Time: 45min		value before test and after test is 50% larger; 2. Function defect :	
		Drop direction: 1 corner/3 edges/6 s	ides 10 time	Non-display,abnormal-d isplay,missing lines, Short lines,ITO	
		Packing weight(kg)	Drop height(cm)	corrosion;	
10.8	Drop test	<10	80±1.6	3.Visual defect : Air bubble in the LCD,Seal	
10.0		11~20	60±1.2	leak,Glass crack.	
		21~30	50±1.0		
		31~40	40±0.8		
10.9	ESD test	Air discharge: ±8KV, 10time Contact discharge: ±4KV, 10time			

Remark :

1. The test samples should be applied to only one test item.

2.Sample size for each test item is 3~5pcs.

3.For High temperature high humidity test, Pure water(Resistance>10M $\Omega$ ) should be used.

4.In case of malfunction defect caused by ESD damage, if it would be recovered to normal state after resetting, it would be judged as a good part.

5.B/L evaluation should be excepted from reliability test with humidity and temperature: Some defects such as black spot/blemish can happen by natural chemical reaction with humidity and Fluorescence B/L has. 6.Failure judgment criterion: Basic specification, Electrical characteristic, Mechanical characteristic, Optical characteristic.

### **11. INSPECTION CRITERION**

### 11.1 Objective

The TFT test criterion are set to formalize TFT quality standards for ODNA with reference to those of the customer for inspection, release and acceptance of finished TFT products in order to guarantee the quality of TFT products required by the customer.

### 11.2. Scope

The criterion is applicable to all the TFT products manufactured by ODNA.

#### **11.3. Equipment for Inspection**

Electrical tester, electrical testing machines, vernier calipers, microscopes, magnifiers, anti-static wrist straps, finger cots, labels, tri-phase cold and hot shock machine, constant temperature and humidity chamber, backlight table, ovens for high-low temperature experiments, refrigerators, constant voltage power supply (DC), desk Lamps, etc.

### 11.4. Sampling Plan and Reference Standards

11.4.1 Sampling plan :

Refer to National Standard GB/T 2828.1---2012/ISO2859-1:1999, level II of normal levels :

#### Major defect: AQL 0.4

#### Minor defect: AQL 1.0

11.4.2 GB/T 2828.1---2012/ISO2859-1:1999 Sampling check procedure in count

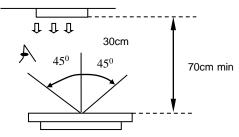
11.4.3 GB/T 18910. Standard for LCM parts

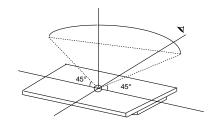
11.4.4 GB/T24213-2008 Basic Environmental Test Procedures for Electrical and Electronic Products 11.4.5 IPC-A-610E Acceptability of Electronic Assemblies

### **11.5. Inspection Conditions and Inspection Reference**

11.5.1 Cosmetic inspection: shall be done normally at 23±5°C of the ambient temperature and 45~75%RH of relative humidity, under the ambient luminance between 500lux~1000lux and at the distance of 30cm apart between the inspector's eyes and the LCD panel and normally in reflected light. For backlight LCM, cosmetic inspection shall be done under the ambient luminance less than 100lux with the backlight on.

11.5.2 The TFT shall be tested at the angle of 45° left and right and 0-45° top and bottom as the following picture showing:





11.5.3 Definition of viewing area(VA)

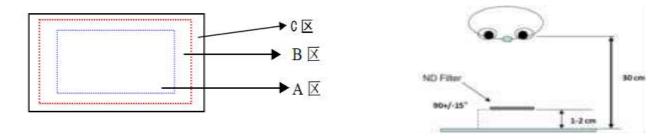
A area : Active area(AA area)

B area : Viewing area(VA area)

C area : Non-viewing area(not viewing after customer assembly)

If there is any appearance viewing defect which do not affect product quality and customer assembly in C area, it's accepted in generally.

The criteria apply to A and B area except chipping and crack.



1<u>1.5.4</u> Inspection with naked eyes(exclusive of the inspection of the physical dimensions of defects carried out

with magnifiers)

11.5.5 ND card use method(refer to right conner image) and scope: Multi-bright dot; Mura(Black/Gray pattern uneven); drak line and so on.

11.5.6 Undefined items or other special items, refer to mutual agreement and limited sample. If criterion does not match product specifications/ technical requirement, both should be subject to special inspection criterion agreed by customer.

### 11.6. Defects and Acceptance Standards

#### 11.6.1 Electrical properties test

11.6.1.1 Test voltage(V) : Refer to the instruction of testers and the product specification or drawing and the display content and parameters and display effects shall conform to the product specification and drawing. 11.6.1.2 Current Consumption(I) : Refer to approved product specifications or drawings.

11.6.1.3 Function items(Defect category : MA.)

No.	Defects	Descriptions	Pictures	Inspection method/tools	Defect category
11.6.1.3.1		shows no picture/display in normal connected situation.		Naked eyes/ testers	MA.
11.6.1.3.2	Missing segment	Shows missing lines in normal display		Naked eyes/ testers	MA.
11.6.1.3.3	Dark line	Only visible on gray pattern, 1 or more vertical/horizontal lines:5%ND,not visible,OK	/	Naked eyes/ testers	MA.
11.6.1.3.4	POL angle defect	Not accepted	т: W F: W F: SL JA / S A / S	Naked eyes/ testers	MA.
11.6.1.3.5	Image retention (sticking)	Chess pattern stays for 30mins and change to 50% gray pattern,disappear time <10s, OK; if time>10s, NG		Naked eyes/ testers	MA.
11.6.1.3.6	Flicker	Refer to limit sample if essential or flicker value<-30dB(measured by CA310A); OK		Naked eyes/ CA310A	MA.
11.6.1.3.7	Display abnormal	Not accepted		Naked eyes/ testers	MA.
11.6.1.3.8	Cross-talk	Refer to limited sample	•	Naked eyes/ limited sample	MA.
11.6.1.3.9	Display dim/bright	Refer to limited sample	/	Naked eyes/ limited sample	MA.
11.6.1.3.10	Contrast	Refer to limited sample	1	Naked eyes/ limited sample	MA.
11.6.1.3.11	Huge current	Out of spec, not accepted	1	Ammeter	MA.
11.6.1.3.12	TP function	Not accepted	1	Naked eyes/ Touch/	MA.

defect		test program	

### 11.6.2 LCD dot/line defect

11.6.2.1 LCD pixel dot defect(defect category : MI.)

Item		Inspection criterion					
Size	S<5"	5"≤S<10"	10"≤S<15"				
Color pixel dot defect(RGB dot)	1	2	2				
2 connected bright dot	0	1	1				
3 connected bright dot or more	0	0	0				
Bright dot quantity	1	2	2				
Random dark dot quantity	2	3	3				
2 connected dark dot	1	1	1				
3 connected dark dot or more	0	0	0				
Dark dot quantity	3	4	4				
Multi-bright dot		ND 3%hidden, OK					
Remark: 2 bright dots distance D	S≥15mm 2 dark dots d	listance DS≥5mm					
1) Bright dot: Power on TFT and RGB dot in black display							
2) Dark dot: Power on TFT and g	ray or black dot in RGB	display					

3) Multi-bright dot: Power on TFT and fluorescent tiny dot in black display(only visible in black display)

### 11.6.2.2 LCD appearance dot defect (defect category : MI.)

Na	ltom		Ins	spection c		Disture	Inspection		
No.	Item	Size		S<5"	5"≤S<10"	10"≤S<15"	Picture	method/tools	
		D≤0	).15	Not count	Not count	D≤0.2mm			
		0.15<	D≤0.25	3	3	Not count	<b>1</b> <sup>b</sup>	Naked eyes	
		0.25<	D≤0.30	1	2	0.2~0.35mm	it a t	/film card	
	Dot defect	0.30 <d≤0.35< td=""><td>0</td><td>1</td><td>Q'ty ≤ 4</td><td></td><td>/magnifier</td></d≤0.35<>		0	1	Q'ty ≤ 4		/magnifier	
11.6.2.2.1	(black dot,	0.35<	D≤0.50	0	0	1	D=(a+b)/2	/magniner	
	white dot)	D>0.5		0	0	0			
		Remark :	D≤0.15m	m, not cou	nt.Multi-dot	as bulk is not	accepted.	·	
		Count do	t quantity≤	≤ 5					
		2 round d	ots or line	ear dots in	1 cm is judo	ged as multi-de	ot.		
		Length (mm)	Width (mm)	S<5"	5"≤S<10"	10"≤S<15"		Naked eyes /film card	
		Not count	W≤0.03	Accepted	Accepted	Accepted			
	Line	L≤5	0.03≤W <0.05	3	3	Not count			
11.6.2.2.2	defect (visible	L≤5	0.05≤W <0.08	0	1	3		/magnifier	
	when power on)	L≤8	0.05≤W <0.08	0	0	1	$( \downarrow$		
		L>8	W>0.08	0					
				-		becial angle ag touched, no c			

	Polarizer	Size(mi	m)	S<	<5"	5"≤S	i<10"	10"≤S<15"			
	convex-	D≤0.2			count		count	Not count			
11 0 0 0 0	concave	0.20 <d≤< td=""><td></td><td colspan="2">2</td><td></td><td>2</td><td>3</td><td></td><td>Naked</td><td>•</td></d≤<>		2			2	3		Naked	•
11.6.2.2.3	dot defect, polarizer	0.50 <d≤ 0.8<d≤< td=""><td></td><td></td><td>0</td><td></td><td>1 0</td><td>1</td><td></td><td>/film /magi</td><td></td></d≤<></d≤ 			0		1 0	1		/film /magi	
	bubble							1	r a 1	/magi	linei
	defect	D>1.5m	ım		0		0	0			
11.6.3 Chippin	ig defect			•							
No.	lte	ltem			Ac	cepte	d crite	rion(mm)		MA.	MI.
11.6.3.1	ITO cond	uctive side	Х			/	:	≤1/8L	/		
	8		Y	,	Y≤1	/6W	1/6W	/ <y≤1 4w<="" td=""><td>1/4W <y< td=""><td></td><td>al</td></y<></td></y≤1>	1/4W <y< td=""><td></td><td>al</td></y<>		al
		STAT 2	Acc	ept		2		2	0		
		2									
	Corner	chipping	Х	(		/		≤1/6L	/		I
	(ITO pins position)		Y		Y≤1	/2W	′2W 1/2W <y≤w< td=""><td>W <y< td=""><td></td><td>V</td></y<></td></y≤w<>		W <y< td=""><td></td><td>V</td></y<>		V
11.6.3.2	×.		Acc	ept		2		1	0		
			Corner chipping occurred in sealed edge position as per 6.3.3; at the same time it should not enter into black border of the frame and the corner chipping effect the electric connection position perform as per 6.3.1.					t enter into er chipping			
	Chipping in sealed area (outside chipping)		Х			/		≤1/8L	/		
				Y(outside chipping) Not ente			Enter Y≤H		H <y< td=""><td></td><td></td></y<>		
			Y(in: chipp			ito alant	١	Enter ∕≤1/2H	1/2H <y< td=""><td></td><td></td></y<>		
11.6.3.3	z 🖌 🔨	¥	Z	2	≤	T		≤1/2T	/		$\checkmark$
		- Aller	Acc	ept		2		1	0		
	Chipping in sealed area (inside chipping)		The standards of inner and outer chipping on edge sealing area are same. When the chipping occurred in the opposite of stage, Y as per the chipping on the non-conduction side standard in 6.3.1					ng occurred			
		tive side e chipping)	Х		,	1		≤1/6L	/		
11.6.3.4			Y		Y≤1	/3W	1/3W	/ <y≤2 3w<="" td=""><td>2/3W <y< td=""><td></td><td></td></y<></td></y≤2>	2/3W <y< td=""><td></td><td></td></y<>		
11.0.3.4			Acc	ept		2		2	0		
			Chipping into ITO side, refer to 6.3.1								
11.6.3.5	Protruding	LCD poor	Х			/		≤1/8L	/		$\checkmark$

AFY1280800A0-10.1INTH-R

Page 19

↓ ↓ ↓

	cutting and LCD burrs	Y	≤1/6W	1/6W <y≤1 5w<="" th=""><th>1/5W <y< th=""><th></th></y<></th></y≤1>	1/5W <y< th=""><th></th></y<>	
		Z	/	/	/	
		Accept	1	1	1	
		The outside drawing.	e protruding	control as per the t	olerance of	
11.6.3.6	Crack	Not allow t	o occur crac	ks;		
Remark : X means the Y means the	length of chipping; width;					

Z means the thickness;

W means the step width of the two glasses;

H means the distance from the glass edge to the sealant inner edge;

T means glass thickness.

11.6.4 Backlight components

No.	ltem	Description	Accepted criterion	MA.	MI.
11.6.4.1	No backlight wrong Color	/	Rejected	$\checkmark$	
11.6.4.2	Color deviation	When powered on, the LCD color differs from its sample and found that the color not conforming to the drawing after testing.	Refer to sample and drawing		
11.6.4.3	Brightness deviation	When powered on, the LCD brightness differs from its sample and is found after testing not conforming to the drawing; or if it conforms to the drawing but the brightness over ±40% than its typical value.	Refer to sample and drawing		$\checkmark$
11.6.4.4	Uneven brightness	Uneven on the same LCD and out of the specification of the drawing. The no specification evenness= (the max value-the min value)/ mean value< 70%.	Refer to sample and drawing		$\checkmark$
11.6.4.5	Spot/line/ scratch	When power on, it has dirty spot, scratches and so on spot and line defects.	Refer to 6.2.2		

### 11.6.5 Metal frame (Metal Bezel)

No.	ltem	Description	Accepted criterion	MA.	MI.
11.6.5.1	Material & surface treatment	Metal frame/surface treatment do not conform to the specifications.	Rejected		
11.6.5.2	Tab twist Unconformity /Tab not twisted	Wrong twist method or direction and twist tabs are not twisted as required.	Rejected	$\checkmark$	
11.6.5.3	Bezel paint loss	1.Front surface : Paint peel off and scratch to the bottom	Rejected		$\checkmark$

Painting peel off, discoloration, dent, and scratch       Chine there is off scratch to the bottom Dot: D51.0mm, exceeds 3; Line.LS.0mm,WS0.05mm, exceeds 2;       vi         11.6.5.6       Burr       Burr(5) on metal bezel is so tong as to get into viewing area.       Rejected       vi         11.6.5.6       Burr       Dimension in drawing spec.       Rejected       vi         11.6.6.1       Model &P/N       Material model & P/N       Keep the same with drawing and technical requirement       vi         11.6.6.1       Model &P/N       Material model & P/N       Keep the same with drawing and technical requirement       vi         11.6.6.2       Dimension / position       Dimension in drawing spec       Keep the same with drawing and technical requirement       vi         11.6.6.2       Dimension / position       Remark: H=ITO pin length f=FPC width W=ITO pin width       Second technical requirement       vi         11.6.6.3       FPC appearance       Hot pressing material get broken, folding line open; material which cause line short       Broken length<2mm; h2       vi         11.6.6.3       FPC burr       Burr near FPC edge area       When cover line and broken-sRejected       vi         11.6.6.4       FPC burr       Burr near FPC edge area       Vire regit scloading       vi         11.6.6.5       FPC folling off       Sealant issing ITO       Sealant is not co	11.6.5.4	Bezel scratch	Dot:D≤0.5mm, exceeds 3; Line:L≤3.0mm,W≤0.05mm exceeds 2; 2.Front dent, air bubble and side with			$\checkmark$
I1.6.5.1       Built       long as to get into viewing area.       Rejected       V         11.6.6 FPC       No.       Item       Description       Accepted criterion       MA.       MI.         11.6.6.1       Model &P/N       Material model & P/N       Keep the same with drawing and technical requirement       V         11.6.6.1       Model &P/N       Material model & P/N       Keep the same with drawing and technical requirement       V         11.6.6.2       Dimension/ position       Dimension in drawing spec       If 3/3w, h ≤1/3H, dimension in drawing spec->OK Conductive material and ITO/PDA connective area must over than 1/2.       Entire dimension must be in spec tolerance.       V         11.6.6.2       Dimension/ position       Remark: H=ITO pin length f=FPC width W=ITO pin width       Hot pressing material get broken, folding line open: FPC golden finger oxidate, broken, scratch ,foreign material which cause line short       Broken length<2mm; FPC line is OK-> no cut trace* and 'no exposed copper Accepted         11.6.6.3       FPC burr       Burr near FPC edge area       When cover line and burr length stiller and ine broken, scratch ,foreign material which cause line short       V         11.6.6.4       FPC colding area falling off ; silica gel broken, for fing       FPC conding area falling off ; silica gel Rejected       V         11.6.6.7       Sealant missing ITO line       Sealant is not covered all ITO line       Rejected	11.6.5.5	off, discoloration, dent, and	paint peeling off scratch to the bottom Dot: $D \le 1.0 \text{ mm}$ , exceeds 3;			$\checkmark$
No.         Item         Description         Accepted criterion         MA.         MI.           11.6.6.1         Model &P/N         Material model & P/N         Keep the same with drawing and technical requirement         v           11.6.6.1         Model &P/N         Dimension in drawing spec         fs1/3w, h s1/3H, dimension in drawing spec-> OK Conducive material and ITO/PDA         v           11.6.6.2         Dimension/ position         Remark: H=ITO pin length f=FPC width W=ITO pin width         fs1/3w, h s1/3H, dimension in drawing spec-> OK Conducive material and ITO/PDA         v           11.6.6.3         FPC appearance         Hot pressing material get broken, folding line open; FPC golden finger oxidate, broken scratch, foreign material which cause line short         Broken length<2mm; FPC line is OK -> no cut trace* and 'no exposed copper Accepted         v/           11.6.6.4         FPC bourn         Burr near FPC edge area         When cover line and burr length s1.6.6.5         v/           11.6.6.5         FPC falling off         FPC bonding area falling off ; silica gel breaking         Rejected         v/           11.6.6.7         Missing sealant         No sealant         Rejected         v/           11.6.6.8         Sealant         Sealant height ->product total height         Rejected         v/	11.6.5.6	Burr		Rejected		$\checkmark$
11.6.6.1       Model &P/N       Material model & P/N       Keep the same with drawing and technical requirement drawing and technical requirement drawing spec.       V         11.6.6.1       Dimension in drawing spec       Dimension in drawing spec.       Keep the same with drawing spec.       V         11.6.6.2       Dimension/ position       Dimension in drawing spec.       Keep the same with drawing spec.       V         11.6.6.2       Dimension/ position       Remark: H=ITO pin length feFPC width W=ITO pin width       Fere dimension must be in spec tolerance.       V         11.6.6.3       FPC appearance       Hot pressing material get broken, folding line open; FPC golden finger oxidate, broken, speceded       Broken length<2mm; FPC line is OK -> no cut trace' and 'no exposed copper Accepted Crack and line broken.>Regeted       V         11.6.6.4       FPC burr       Burr near FPC edge area       When cover line and burr length s1.0mm>Accepted       V         11.6.6.5       Sealant mis not covered all ITO line       Rejected       V       V         11.6.6.7       Missing ITO line       Sealant is not covered all ITO line       Rejected       V         11.6.7.SMT       Sealant height ->product total height       Rejected       V       V	11.6.6 FPC	T	- -			
11.6.6.1       Model &P/N       Material model & P/N       drawing and technical requirement       √         11.6.6.1       Dimension in drawing spec       Dimension in drawing spec       fs1/3w, h ≤1/3H, dimension in drawing spec > OK Conducive material and ITC/PDA councive area must over than 1/2. Entire dimension must be in spec tolerance.       √         11.6.6.2       Dimension/ position       Remark: H=ITO pin length f=FPC width W=ITO pin width       Firstowidth       N         11.6.6.3       FPC appearance       Hot pressing material get broken, folding line open; FPC golden finger oxidate, broken, socrath, foreign material which cause line short       Broken length<2mm; FPC line is OK > no cut trace' and 'no exposed copper Accepted Crack and line broken->Rejected         11.6.6.4       FPC burr       Burr near FPC edge area       When cover line and burr length s1.0mm->Accepted         11.6.6.5       Sealant missing ITO line       Sealant is not covered all ITO line       Rejected       √         11.6.6.7       Missing sealant       Sealant height ->product total height       Rejected       √	No.	Item	Description	Accepted criterion	MA.	MI.
11.6.6.2       Dimension/ position       Dimension/ Position	11.6.6.1	Model &P/N	Material model & P/N	drawing and technical	$\checkmark$	
11.6.6.3       FPC appearance       Hot pressing material get broken, folding line open; FPC golden finger oxidate, broken, scratch ,foreign material which cause line short       FPC line is OK- > no cut trace" and "no exposed copper Accepted Crack and line broken->Rejected         11.6.6.4       FPC burr       Burr near FPC edge area       When cover line and burr length ≤1.0mm->Accepted         11.6.6.5       FPC falling off       FPC bonding area falling off ; silica gel breaking       Rejected       √         11.6.6.6       Sealant missing ITO line       Sealant is not covered all ITO line       Rejected       √         11.6.6.7       Missing sealant       Sealant       Sealant       Rejected       √         11.6.6.8       Sealant       Sealant height ->product total height       Rejected       √         11.6.7       Smith Sealant height ->product total height       Rejected       √	11.6.6.2		Remark: H=ITO pin length f=FPC width	dimension in drawing spec-> OK Conducive material and ITO/PDA connective area must over than 1/2. Entire dimension must be in spec tolerance.		V
11.6.6.4FPC burrBurr near FPC edge areaburr length $\leq 1.0$ mm->Accepted $$ 11.6.6.5FPC falling offFPC bonding area falling off ; silica gel breakingRejected $$ 11.6.6.6Sealant missing ITO lineSealant is not covered all ITO lineRejected $$ 11.6.6.7Missing sealantNo sealantRejected $$ 11.6.6.8SealantSealant height ->product total heightRejected $$ 11.6.7 SMTSealantSealant height ->product total heightRejected $$	11.6.6.3		folding line open; FPC golden finger oxidate, broken ,scratch ,foreign	FPC line is OK- > no cut trace" and "no exposed copper Accepted Crack and line		V
11.6.0.5offbreakingRejected $$ 11.6.6.6Sealant missing ITO lineSealant is not covered all ITO lineRejected $$ 11.6.6.7Missing sealantNo sealantRejected $$ 11.6.8SealantSealant height ->product total heightRejected $$ 11.6.7 SMTSealantSealantSealant height ->product total heightRejected $$	11.6.6.4	FPC burr	Burr near FPC edge area	burr length		$\checkmark$
11.6.6.6       missing ITO line       Sealant is not covered all ITO line       Rejected       √         11.6.6.7       Missing sealant       No sealant       Rejected       √         11.6.6.8       Sealant       Sealant height ->product total height       Rejected       √         11.6.7 SMT       Intervention       Intervention       Intervention       Intervention	11.6.6.5	-		Rejected		$\checkmark$
11.6.0.7     sealant     No sealant     Rejected     √       11.6.6.8     Sealant     Sealant height ->product total height     Rejected     √       11.6.7 SMT	11.6.6.6	missing ITO	Sealant is not covered all ITO line	Rejected	$\checkmark$	
11.6.7 SMT	11.6.6.7		No sealant	Rejected	$\checkmark$	
	11.6.6.8	Sealant	Sealant height ->product total height	Rejected	$\checkmark$	
No. Item Description Accepted criterion MA. MI.	11.6.7 SMT					
	No.	Item	Description	Accepted criterion	MA.	MI.

11.6.7.1	Soldering bridge	Solder between adjacent pads and components	Rejected		$\checkmark$
11.6.7.2	Solder ball/splash	Solder ball/tin dross causing short circuit at the solder point. There are active solder ball and splash.	Rejected		$\checkmark$
11.6.7.3	Soldering excursion	Soldering slant > 1/3 soldering pad	Rejected		V
11.6.7.4	Component wrong	Component on PCB differs with drawing: wrong one, extra one,lack one,opposite polarity	Rejected	$\checkmark$	
	attaching	JUMP short circuit on PCB: extra soldering ,lack soldering.	Rejected	$\checkmark$	
11.6.7.5	Component falling off	Soldering but component is missing	Rejected	$\checkmark$	
11.6.7.6	Wrong component	Component model/spec differs from product specification	Rejected	$\checkmark$	
	Appearance				
11.6.8 Genera No.	Item	Description	Accepted criterion	MA.	MI.
	Item Dimension	According to drawing	Accepted criterion Accepted	MA. √	MI.
No.	Item	•	Accepted Rejected		<b>MI.</b> √
No. 11.6.8.1	Item Dimension Surface	According to drawing Defect mark or label are not removed	Accepted		
No. 11.6.8.1 11.6.8.2	Item Dimension Surface stain Assembly foreign	According to drawing Defect mark or label are not removed residual glue, and finger print,etc; Dot/linear stain after assembly backlight and diffuse film TP assembly fogy stain Different model product	Accepted Rejected Invisible when power on->OK Refer to 6.2.2 dot/line		√
No. 11.6.8.1 11.6.8.2 11.6.8.3	Item Dimension Surface stain Assembly foreign material	According to drawing Defect mark or label are not removed residual glue, and finger print,etc; Dot/linear stain after assembly backlight and diffuse film TP assembly fogy stain	Accepted Rejected Invisible when power on->OK Refer to 6.2.2 dot/line spec Rejected Rejected	√	√
No.           11.6.8.1           11.6.8.2           11.6.8.3           11.6.8.4	Item Dimension Surface stain Assembly foreign material Mixture Product mark Componen t mark	According to drawing Defect mark or label are not removed residual glue, and finger print,etc; Dot/linear stain after assembly backlight and diffuse film TP assembly fogy stain Different model product in the same shipment Missing, unclear, incorrect,	Accepted Rejected Invisible when power on->OK Refer to 6.2.2 dot/line spec Rejected	√	√ √
No.           11.6.8.1           11.6.8.2           11.6.8.3           11.6.8.4           11.6.8.5	Item Dimension Surface stain Assembly foreign material Mixture Product mark Componen	According to drawing Defect mark or label are not removed residual glue, and finger print,etc; Dot/linear stain after assembly backlight and diffuse film TP assembly fogy stain Different model product in the same shipment Missing, unclear, incorrect, or misplaced part Silk screen mark clear, resistance	Accepted Rejected Invisible when power on->OK Refer to 6.2.2 dot/line spec Rejected Rejected Accepted (Refer to customer	√	√ √ √

11.6.8.9	Light leak	1.LCD edge(near backlight) shadow by LCD lamps irregular illuminate 2.Judge in black/white/gray display (slight leaky is yellowish,greenish, blueish ->NG); Tape 浮地 派光	Refer to limited sample	$\checkmark$
11.6.8.10	Polarizer	<ul><li>1.Polarizer slant.Cover VA and not over</li><li>LCD edge</li><li>2.No unmovable stain or finger print in polarizer VA</li><li>3.Bubble/warped but not enter VA</li></ul>	Accepted	$\checkmark$
11.6.8.11	TP defect	1.TP crack 2.TP stain(fogy& unremovable) 3.TP glue overflow to VA	Rejected	

#### Remark :

Anything which is not clearly defined in 6.5~6.8 should refer to IPC-A-610E.Consumer Electronics,

Non-consumer Electronics refer to I grade and Industrial, Automobile refer to II grade.

### 11.7 Others

Items not specified in this document or released on compromise should be inspected with reference to mutual agreement and limit samples.

### **12. HANDLING PRECAUTIONS**

### 12.1 Mounting method

The LCD module consists of two thin glass plates with polarizes which easily be damaged. And since the module in so constructed as to be fixed by utilizing fitting holes in the printed circuit board. Extreme care should be needed when handling the LCD modules.

### 12.2 Caution of LCD handling and cleaning

When cleaning the display surface, Use soft cloth with solvent

[recommended below] and wipe lightly :

- •.lsopropyl alcohol
- Ethyl alcohol

Do not wipe the display surface with dry or hard materials that will damage the polarizer surface. Do not use the following solvent :

- •.Water
- Aromatics

Do not wipe ITO pad area with the dry or hard materials that will damage the ITO patterns Do not use the following solvent on the pad or prevent it from being contaminated :

- Soldering flux
- •.Chlorine (Cl) , Sulfur (S)

If goods were sent without being silicon coated on the pad, ITO patterns could be damaged due to the corrosion as time goes on.

If ITO corrosion happen by miss-handling or using some materials such as Chlorine (CI), Sulfur (S) from customer, Responsibility is on customer.

### 12.3 Caution against static charge

The LCD module use C-MOS LSI drivers, so we recommended that you :

Connect any unused input terminal to Vdd or Vss, do not input any signals before power is turned on, and ground your body, work/assembly areas, assembly equipment to protect against static electricity.

#### 12.4 Packing

Module employ LCD elements and must be treated as such.

• Avoid intense shock and falls from a height.

•. To prevent modules from degradation, do not operate or store them exposed direct to sunshine or high temperature/humidity.

### 12.5 Caution for operation

•. It is an indispensable condition to drive LCD's within the specified voltage limit since the higher voltage then the limit cause the shorter LCD life.

•. An electrochemical reaction due to direct current causes LCD's undesirable deterioration, so that the use of direct current drive should be avoided.

•.Response time will be extremely delayed at lower temperature then the operating temperature range and on the other hand at higher temperature LCD's how dark color in them. However those phenomena do not mean malfunction or out of order with LCD's, which will come back in the specified operation temperature.

•. If the display area is pushed hard during operation, some font will be abnormally displayed but it resumes normal condition after turning off once.

•.A slight dew depositing on terminals is a cause for electro-chemical reaction resulting in terminal open circuit.

•. Usage under the maximum operating temperature, 50%Rh or less is required.

•. When fixed patterns are displayed for a long time, remnant image is likely to occur.

### 12.6 Storage

In the case of storing for a long period of time for instance, for years for the purpose or replacement use, the following ways are recommended.

•.Storing in an ambient temperature 10°C to 30°C, and in a relative humidity of 45% to 75%. Don't expose to sunlight or fluorescent light.

•.Storing in a polyethylene bag with the opening sealed so as not to enter fresh air outside in it . And with no desiccant.

•.Placing in a dark place where neither exposure to direct sunlight nor light's keeping the storage temperature range.

•.Storing with no touch on polarizer surface by the anything else.

It is recommended to store them as they have been contained in the inner container at the time of delivery from us.

### 12.7 Safety

•. It is recommendable to crash damaged or unnecessary LCD's into pieces and wash off liquid crystal by either of solvents such as acetone and ethanol, which should be burned up later.

•. When any liquid leaked out of a damaged glass cell comes in contact with your hands, please wash it off well with soap and water.

### **13. PRECAUTION FOR USE**

**13.1** A limit sample should be provided by the both parties on an occasion when the both parties agreed its necessity. Judgment by a limit sample shall take effect after the limit sample has been established and confirmed by the both parties.

**13.2** On the following occasions, the handing of problem should be decided through discussion and agreement between responsible of the both parties.

•.When a question is arisen in this specification.

•.When a new problem is arisen which is not specified in this specifications.

•.When an inspection specifications change or operating condition change in customer is reported to ODNA, and some problem is arisen in this specification due to the change.

•. When a new problem is arisen at the customer's operating set for sample evaluation in the customer site.

### **14. PACKING SPECIFICATION**

Please consult our technical department for detail information.